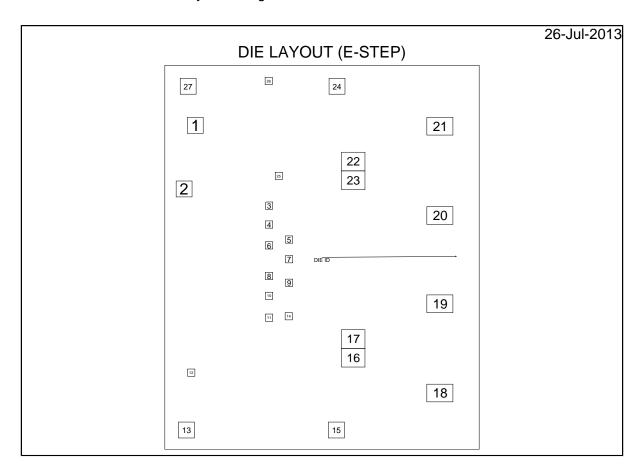


LM2588-5.0-MWC SIMPLE SWITCHER 5A Flyback Regulator with Shutdown



DIE/WAFER CHARACTERISTICS

DIE/WAFER CHARA	CIERISTICS			
Fabrication Attributes		General Die Information		
Physical Die	LM1587E-5.0	Bond Pad Opening	180.00μm x 180.00μm	
Identification		Size (min)		
Die Step	E	Bond Pad Metalization	0.5%CU	
Physical Attributes		Passivation	PECVDOX NITRIDE	
Wafer Diameter	200mm	Back Side Metal	TINIAG	
Die Size (Drawn)	3556.000μm	Back Side Connection	Floating	
	x 4343.400µm			
	140.0mils x 171.0mils			
Thickness	330.2µm Nominal			
Min Pitch	450.17μm			
Note: All values are rounded to the nearest micron.				
Special Assembly Requirements:				



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Die Bond Pad Coordinate Locations(E-Step) (Referenced to die center, coordinates in μ m) NC = No Connection, N.U. = Not Used Signal Name Pad Number X/Y Coordinates Pad Size Χ Χ Υ Υ Feedback 1 -1434.00 1492.50 180.00 180.00 Х GND 2 -1560.00 773.50 180.00 180.00 Х NC 3 -599.00 585.00 82.00 82.00 Χ 4 NC -599.00 371.00 82.00 Х 82.00 NC 5 -372.00 201.50 82.00 82.00 Χ NC 6 82.00 -599.00 135.00 Х 82.00 NC 7 -372.00 -21.50 82.00 82.00 Х NC 8 -599.00 -211.00 82.00 82.00 Х NC 9 -372.00 -287.50 82.00 82.00 Х NC 10 -599.00 -435.50 82.00 82.00 Χ NC 11 -599.00 -682.50 82.00 Х 82.00 NC 12 -1479.00 -1304.5082.00 82.00 Х 180.00 Freq. Sync. 13 -1534.00 -1953.50 180.00 Х NC 14 -376.00 -666.50 82.00 82.00 Х 180.00 Vin 15 163.00 -1953.50 Х 180.00 Switch 16 353.00 -1135.50 266.00 211.00 Х Switch 17 353.00 -924.50 266.00 Х 211.00 **GND** 18 1333.50 200.00 -1535.00 295.00 Х GND 19 1333.50 -525.00 295.00 200.00 Х **GND** 20 1333.50 473.00 295.00 200.00 Х **GND** 21 1333.50 1483.00 295.00 200.00 Х Switch 22 353.00 1083.50 266.00 211.00 Χ Switch 23 353.00 872.50 266.00 211.00 Х Freq. Adj. -- On/Off 24 170.00 1935.50 180.00 180.00 Х NC 25 -488.00 921.50 82.00 82.00 Х NC 26 -602.50 1995.50 82.00 Х 82.00 Compensation 27 -1514.00 1935.50 180.00 Χ 180.00



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